



# M T B F

(EIAJ RCR-9102B)

Model	GT2.5W-12
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No.	Parts	Q'ty of Device	Failure rate [ $10^{-6}/H$ ]	Reference
1	IC	Linear	4	0.0960
2	Transistors	NPN/PNP	0	0.0000
3	Transistors	Power NPN/PNP	2	0.0840
4	FET	MOS FET	2	0.1980
5	Diodes	FR	4	0.0880
6	Diodes	Zener	2	0.0480
7	Diodes	bridge	4	0.2640
8	Resistors	Metal Film	32	0.5120
9	Resistors	Power Film	6	0.2460
10	Resistors	variable	2	0.0320
11	Capacitors	Aluminum Electrolytic	10	0.1900
12	Capacitors	Film	8	0.0672
13	Transformer	Power	1	0.3600
14	Fuses		3	0.0600
15	Connectors	Printed Circuit Board	9	0.4680
16	Connection	Hand Solder	27	0.0702
17	Connection	Flow Solder	296	0.1539
18	Connection	Crimp	45	0.0279
19	Connection	Screw	8	0.0080
20	Printed Circuit Board	Through Hole	4	0.1800
Total Failure Rate [ $10^{-6}/H$ ]			3.1532	

M T B F	[H]	317,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-